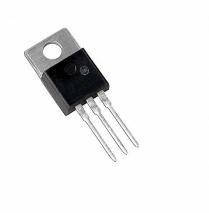


# FDP8D5N10C Datasheet

www.digi-electronics.com



https://www.DiGi-Electronics.com

DiGi Electronics Part Number

FDP8D5N10C-DG

Manufacturer

onsemi

Manufacturer Product Number

FDP8D5N10C

Description

MOSFET N-CH 100V 76A TO220-3

**Detailed Description** 

N-Channel 100 V 76A (Tc) 2.4W (Ta), 107W (Tc) Thro

ugh Hole TO-220-3



Tel: +00 852-30501935

RFQ Email: Info@DiGi-Electronics.com

DiGi is a global authorized distributor of electronic components.



# **Purchase and inquiry**

Manufacturer Product Number:	Manufacturer:
FDP8D5N10C	onsemi
Series:	Product Status:
PowerTrench®	Active
FET Type:	Technology:
N-Channel	MOSFET (Metal Oxide)
Drain to Source Voltage (Vdss):	Current - Continuous Drain (Id) @ 25°C:
100 V	76A (Tc)
Drive Voltage (Max Rds On, Min Rds On):	Rds On (Max) @ ld, Vgs:
10V	8.5mOhm @ 76A, 10V
Vgs(th) (Max) @ ld:	Gate Charge (Qg) (Max) @ Vgs:
4V @ 130μA	34 nC @ 10 V
Vgs (Max):	Input Capacitance (Ciss) (Max) @ Vds:
±20V	2475 pF @ 50 V
FET Feature:	Power Dissipation (Max):
	2.4W (Ta), 107W (Tc)
Operating Temperature:	Mounting Type:
-55°C ~ 175°C (TJ)	Through Hole
Supplier Device Package:	Package / Case:
TO-220-3	TO-220-3
Base Product Number:	
FDP8D5	

# **Environmental & Export classification**

8541.29.0095

RoHS Status:	Moisture Sensitivity Level (MSL):
ROHS3 Compliant	Not Applicable
REACH Status:	ECCN:
REACH Unaffected	EAR99
HTSUS:	



# MOSFET - N-Channel, Shielded Gate, POWERTRENCH®

100 V, 76 A, 8.5 m $\Omega$ 

### FDP8D5N10C, FDPF8D5N10C

#### **General Description**

This N-Channel MV MOSFET is produced using **onsemi**'s advanced POWERTRENCH process that incorporates Shielded Gate technology. This process has been optimized to minimize on-state resistance and yet maintain superior switching performance with best in class soft body diode.

#### **Features**

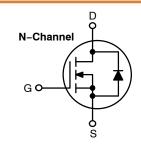
- Max  $R_{DS(on)} = 8.5 \text{ m}\Omega$  at  $V_{GS} = 10 \text{ V}$ ,  $I_D = 76 \text{ A}$
- Extremely Low Reverse Recovery Charge, Qrr
- 100% UIL Tested
- RoHS Compliant

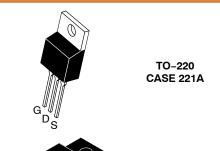
#### **Applications**

- Synchronous Rectification for ATX / Server / Telecom PSU
- Motor Drives and Uninterruptible Power Supplies
- Micro Solar Inverter

V <sub>DS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
100 V	8.5 mΩ @ 10 V	76 A*

<sup>\*</sup>Drain current limited by maximum junction temperature.







#### **MARKING DIAGRAM**



XXX8D5N10C = Device Code (XXX = FDP, FDPF)

A = Assembly Location YWW = Date Code (Year & Week)

ZZ = Assembly Lot

#### **ORDERING INFORMATION**

Device	Package	Shipping
FDP8D5N10C	TO-220	800 Units / Tube
FDPF8D5N10C	TO-220F	1000 Units / Tube

#### **MOSFET MAXIMUM RATINGS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

			Rat	ing	
Symbol		Parameter	FDP8D5N10C	FDPF8D5N10C	Unit
$V_{DS}$	Drain to Source Voltage		100	100	V
$V_{GS}$	Gate to Source Voltage		±20	±20	V
I <sub>D</sub>	Drain Current	– Continuous, T <sub>C</sub> = 25°C (Note 3)	76	76*	Α
		- Continuous, T <sub>C</sub> = 100°C (Note 3)	54	54*	
		- Pulsed (Note 1)	304	304*	
E <sub>AS</sub>	Single Pulsed Avalanche I	Energy (Note 2)	181		mJ
$P_{D}$	Power Dissipation	T <sub>C</sub> = 25°C	107	35	W
		T <sub>A</sub> = 25°C	2.4	2.4	
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Jul	nction Temperature Range	–55 to	+175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. \*Drain current limited by maximum junction temperature.

- Pulsed Id please refer to Figure 11 and Figure 12 "Forward Bias Safe Operating Area" for more details.
   E<sub>AS</sub> of 181 mJ is based on starting T<sub>J</sub> = 25°C, L = 3 mH, I<sub>AS</sub> = 11 A, V<sub>DD</sub> = 100 V, V<sub>GS</sub> = 10 V. 100% test at L = 0.3 mH, I<sub>AS</sub> = 25 A.
   Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	FDP8D5N10C	FDPF8D5N10C	Unit
R <sub>θJC</sub> Thermal Resistance, Junction to Case		1.4	4.2	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	62.5	62.5	

### **ELECTRICAL CHARACTERISTICS** ( $T_J = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHAR	ACTERISTICS			•		
BV <sub>DSS</sub>	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	100	-	-	٧
$\Delta BV_{DSS}$	Breakdown Voltage Temperature	I <sub>D</sub> = 250 μA, referenced to 25°C	-	57	-	mV/°C
$\Delta T_{J}$	Coefficient					
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 80 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ
		V <sub>DS</sub> = 80 V, T <sub>J</sub> = 150°C	-	-	500	μΑ
I <sub>GSS</sub>	Gate to Source Leakage Current	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0 V	-	-	±100	nA
ON CHARA	CTERISTICS					
V <sub>GS(th)</sub>	Gate to Source Threshold Voltage	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 130 μA	2.0	3.0	4.0	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 76 A	-	7.4	8.5	mΩ
9FS	Forward Transconductance	V <sub>DS</sub> = 5 V, I <sub>D</sub> = 76 A	-	68	-	S
DYNAMIC (	CHARACTERISTICS					
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> = 50 V, V <sub>GS</sub> = 0 V, f = 1 MHz	-	1765	2475	pF
C <sub>oss</sub>	Output Capacitance		-	1010	1415	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	16	25	pF
Rg	Gate Resistance		0.1	0.8	1.6	Ω
SWITCHING	G CHARACTERISTICS					
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 50 \text{ V}, I_D = 76 \text{ A}, V_{GS} = 10 \text{ V},$	-	12	22	ns
t <sub>r</sub>	Rise Time	$R_{GEN} = 6 \Omega$	-	11	20	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	18	28	ns
t <sub>f</sub>	Fall Time		-	4	10	ns
Qg	Total Gate Charge	$V_{GS}$ = 0 V to 10 V, $V_{DD}$ = 50 V, $I_D$ = 76 A	-	25	34	nC
$Q_{gs}$	Gate to Source Gate Charge	V <sub>DD</sub> = 50 V, I <sub>D</sub> = 76 A	-	9	-	nC
$Q_{gd}$	Gate to Drain "Miller" Charge		-	5	-	nC
Q <sub>oss</sub>	Output Charge	V <sub>DD</sub> = 50 V, V <sub>GS</sub> = 0 V	-	68	-	nC
DRAIN-SO	URCE DIODE CHARACTERISTICS					
IS	Maximum Continuous Drain to Source Di	ode Forward Current	-	-	76	Α
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode	Forward Current	-	-	304	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 76 A	-	1.0	1.3	٧
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, V_{DD} = 50 \text{ V}, I_F = 76 \text{ A},$	-	58	92	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dl <sub>F</sub> /dt = 100 A/μs	-	53	85	nC
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 \text{ V}, V_{DD} = 50 \text{ V}, I_F = 76 \text{ A},$	-	51	81	ns
Q <sub>rr</sub>	Reverse Recovery Charge	dI <sub>F</sub> /dt = 300 A/μs	-	141	226	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

Normalized

A<sub>DS(on)</sub>, Drain to Source On-Resistance (mΩ)

#### TYPICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted)

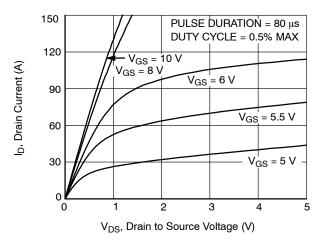


Figure 1. On-Region Characteristics

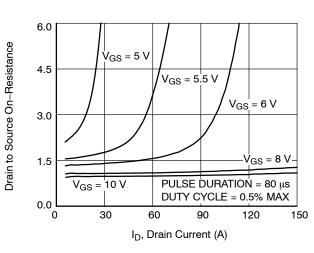


Figure 2. Normalized On–Resistance vs.
Drain Current and Gate Voltage

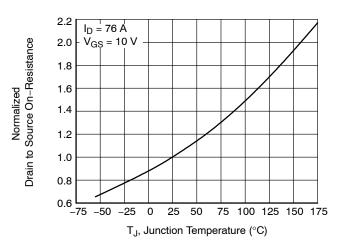


Figure 3. Normalized On–Resistance vs. Junction Temperature

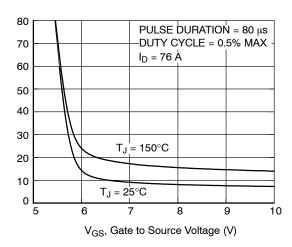


Figure 4. On-Resistance vs. Gate to Source Voltage

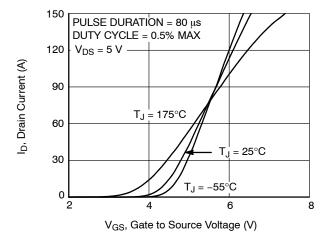


Figure 5. Transfer Characteristics

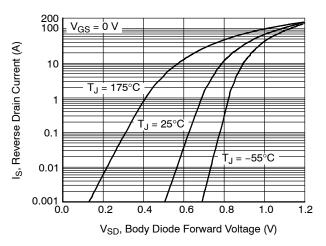


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

#### TYPICAL CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted) (continued)

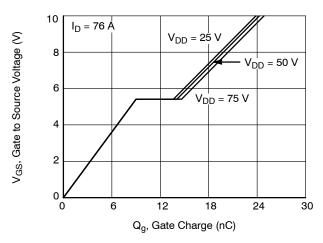


Figure 7. Gate Charge Characteristics

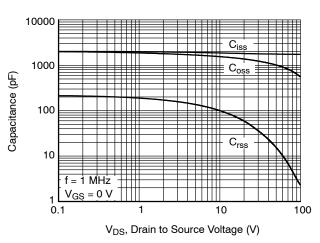


Figure 8. Capacitance vs. Drain to Source Voltage

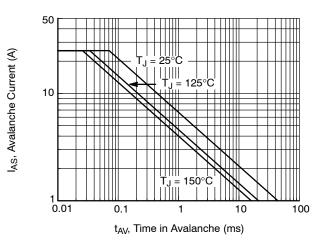


Figure 9. Unclamped Inductive Switching Capability

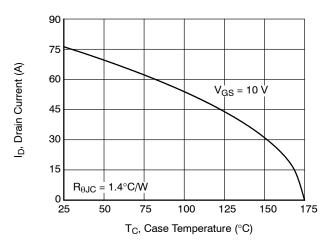


Figure 10. Maximum Continuous
Drain Current vs. Case Temperature
for FDP8D5N10C

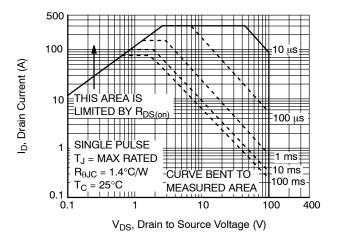


Figure 11. Forward Bias Safe Operating
Area for FDP8D5N10C

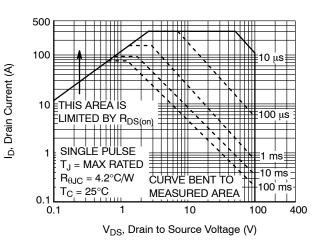
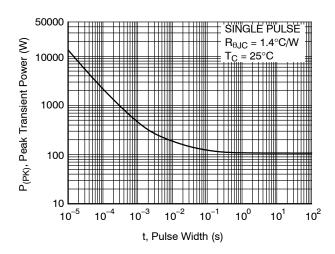


Figure 12. Forward Bias Safe Operating
Area for FDPF8D5N10C

#### TYPICAL PERFORMANCE CHARACTERISTICS (T<sub>J</sub> = 25°C unless otherwise noted) (continued)



50000 P<sub>(PK)</sub>, Peak Transient Power (W)  $R_{\theta JC} = 4.2^{\circ}C/W$ = 25°C 10000 1000 100 10  $10^{-3}$  $10^{-5}$  $10^{-4}$  $10^{-2}$ 10<sup>0</sup>  $10^{-1}$ 10<sup>1</sup> 10<sup>2</sup> t, Pulse Width (s)

Figure 13. Single Pulse Maximum Power Dissipation for FDP8D5N10C

Figure 14. Single Pulse Maximum Power Dissipation for FDPF8D5N10C

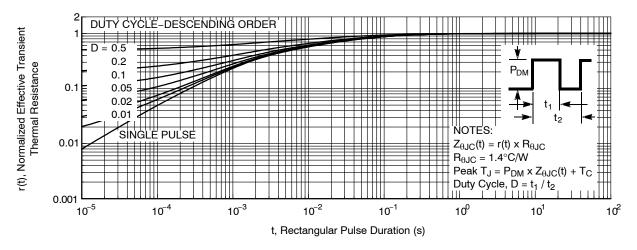


Figure 15. Junction-to-Case Transient Thermal Response Curve for FDP8D5N10C

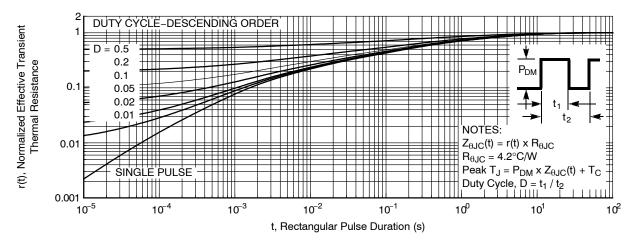


Figure 16. Junction-to-Case Transient Thermal Response Curve for FDPF8D5N10C

FDP8D5N10C onsemi MOSFET N-CH 100V 76A TO220-3

### FDP8D5N10C, FDPF8D5N10C

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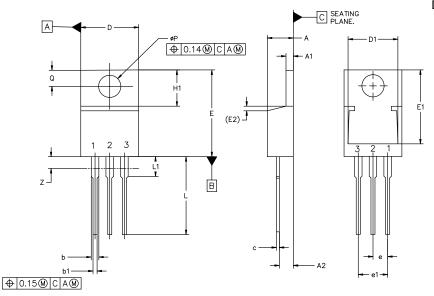
## **MECHANICAL CASE OUTLINE**

PACKAGE DIMENSIONS



#### TO-220-3 10.10x15.12x4.45, 2.54P CASE 221A **ISSUE AL**

**DATE 05 FEB 2025** 



MILLIMETERS						
DIM	MIN	NOM	MAX			
Α	4.07	4.45	4.83			
A1	1.15	1.28	1.41			
A2	2.04	2.42	2.79			
b	1.15	1.34	1.52			
b1	0.64	0.80	0.96			
С	0.36	0.49	0.61			
D	9.66	10.10	10.53			
D1	8.43	8.63	8.83			
E	14.48	15.12	15.75			
E1	12.58	12.78	12.98			
E2	1.27 REF					

MILLIMETERS					
DIM	MIN	NOM	MAX		
е	2.42	2.54	2.66		
e1	4.83	5.08	5.33		
H1	5.97	6.22	6.47		
L	12.70	13.49	14.27		
L1	2.80	3.45	4.10		
Q	2.54	2.79	3.04		
ØΡ	3.60	3.85	4.09		
Z			3.48		

#### NOTES:

- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2018.

  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

STYLE 1:		STYLE 2:		STYLE 3:		STYLE 4:	
PIN 1.	BASE	PIN 1.	BASE	PIN 1.	CATHODE	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	EMITTER	2.	ANODE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	COLLECTOR	3.	GATE	3.	GATE
4.	COLLECTOR	4.	EMITTER	4.	ANODE	4.	MAIN TERMINAL 2
STYLE 5:		STYLE 6:		STYLE 7:		STYLE 8:	
PIN 1.	GATE	PIN 1.	ANODE	PIN 1.	CATHODE	PIN 1.	CATHODE
2.	DRAIN	2.	CATHODE	2.	ANODE	2.	ANODE
3.	SOURCE	3.	ANODE	3.	CATHODE	3.	EXTERNAL TRIP/DELAY
4.	DRAIN	4.	CATHODE	4.	ANODE	4.	ANODE
STYLE 9:		STYLE 10:		STYLE 11:		STYLE 12:	
PIN 1.	GATE	PIN 1.	GATE	PIN 1.	DRAIN	PIN 1.	MAIN TERMINAL 1
2.	COLLECTOR	2.	SOURCE	2.	SOURCE	2.	MAIN TERMINAL 2
3.	EMITTER	3.	DRAIN	3.	GATE	3.	GATE
4.	COLLECTOR	4.	SOURCE	4.	SOURCE	4.	NOT CONNECTED

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DESCRIPTION:	TO-220-3 10.10x15.12x4.45, 2.54P		PAGE 1 OF 1	

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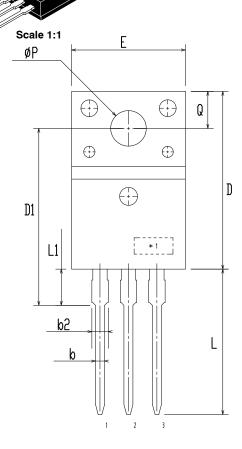


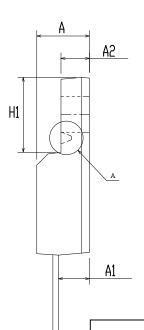
### **MECHANICAL CASE OUTLINE**

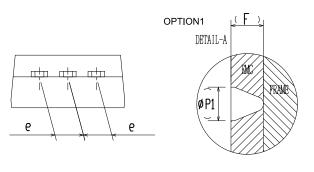
PACKAGE DIMENSIONS

#### TO-220 Fullpack, 3-Lead / TO-220F-3SG CASE 221AT **ISSUE B**

**DATE 19 JAN 2021** 







DIM	MILLIMITERS				
ויונע	MIN	NDM	MAX		
Α	4.50	4.70	4.90		
A1	2.56	2.76	2.96		
A2	2.34	2.54	2.74		
b	0.70	0.80	0.90		
b2	~	2	1.47		
С	0.45	0.50	0.60		
D	15.67	15.87	16.07		
D1	15.60	15.80	16.00		
E	9.96	10.16	10.36		
е	2.34	2.54	2.74		
F	~	0.84	2		
H1	6.48	6.68	6.88		
L	12.78	12.98	13.18		
L1	3.03	3.23	3.43		
ØΡ	2.98	3.18	3.38		
ø P1	~	1.00	~		
Q	3.20	3.30	3.40		

#### NOTES:

- A. DIMENSION AND TOLERANCE AS ASME Y14.5-2009
- B. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUCSIONS.
- C. OPTION 1 WITH SUPPORT PIN HOLE OPTION 2 - NO SUPPORT PIN HOLE

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DESCRIPTION:	TO-220 FULLPACK, 3-LEAD / TO-220F-3SG		PAGE 1 OF 1

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For additional information, please contact your local Sales Representative at www.onsemi.com/support/sales



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